Development of chip-bonding process for GaN/AlGaN-based optoelectronics

Thesis scope

• Literature study to explore thermocompression bonding parameters
• Design of test structures for the bonding process
• Fabrication of test structures in the cleanroom

Methods

• Photolithography
• Dry etching (Reactive Ion Etching) of GaN/AlGaN
• Metal deposition (Evaporation/Sputtering) and lift-off
• Thermocompression bonding

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